# 5-103168-7 - ACTIVE

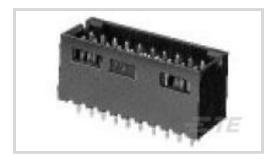
### AMPMODU | AMPMODU Headers

TE Internal #: 5-103168-7 PCB Mount Header, Vertical, Board-to-Board, 18 Position, 2.54 mm [.1 in] Centerline, Fully Shrouded, Gold, Through Hole - Solder, AMPMODU Headers

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### PCB Connector Assembly Type: PCB Mount Header

PCB Mount Orientation: Vertical

Connector System: Board-to-Board

Number of Positions: **18** 

Number of Rows: 2

### Features

### **Product Type Features**

PCB Connector Assembly Type

Connector System

Header Type

PCB Mount Header

Board-to-Board

Fully Shrouded

Connector & Contact	Terminates To
---------------------	---------------

Printed Circuit Board

### **Configuration Features**

Connector Contact Load Condition	Fully Loaded				
PCB Mount Orientation	Vertical				
Number of Positions	18				
Number of Rows	2				
Board-to-Board Configuration	Parallel				
Electrical Characteristics					
Insulation Resistance	5000 ΜΩ				
Dielectric Withstanding Voltage (Max)	750 Vrms				
Body Features					
Connector Profile	Standard				
Primary Product Color	Black				
Contact Features					
Mating Square Post Dimension	.64 mm[.025 in]				

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PCB Contact Termination Area Plating Material Thickness	2.54 – 5.08 μm[100 – 200 μin]
Contact Shape & Form	Square
Contact Underplating Material	Nickel
PCB Contact Termination Area Plating Material	Tin
Contact Base Material	Phosphor Bronze
Contact Mating Area Plating Material	Gold
Contact Mating Area Plating Material Thickness	.762 μm[30 μin]
Contact Type	Pin
Contact Current Rating (Max)	3 A
Termination Features	
Square Termination Post & Tail Dimension	.64 mm[.025 in]
Termination Post & Tail Length	3.18 mm[.125 in]
Termination Method to Printed Circuit Board	Through Hole - Solder
Mechanical Attachment	
Mating Retention	With
Mating Retention Type	Detent Window
Mating Alignment	With

Mating Alignment Tura

Polorization

Mating Alignment Type	Polarization
PCB Mount Retention	Without
PCB Mount Alignment	Without
Connector Mounting Type	Board Mount
Housing Features	
Centerline (Pitch)	2.54 mm[.1 in]
Housing Material	Thermoplastic
Dimensions	
Row-to-Row Spacing	2.54 mm[.1 in]
PCB Thickness (Recommended)	1.4 mm[.055 in]
Usage Conditions	
Housing Temperature Rating	Standard
Operating Temperature Range	-65 – 105 °C[-85 – 221 °F]
Operation/Application	
Circuit Application	Signal

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09/27/2023 08:51AM | Page 2

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### **Industry Standards**

Agency/Standard	CSA
Approved Standards	CSA LR7189, UL E28476
UL Flammability Rating	UL 94V-0
Packaging Features	
Packaging Quantity	96
Packaging Type	Tray
For compliance documentation, visit the product page on TE.com> EU RoHS Directive 2011/65/EU	Compliant
FU RoHS Directive 2011/65/FU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JUNE 2023 (235) Does not contain REACH SVHC
Halogen Content	BFR/CFR/PVC Free, but Br/Cl >900 ppm in other sources

other sources.

### Solder Process Capability

Wave solder capable to 240°C

#### Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

## **Compatible Parts**

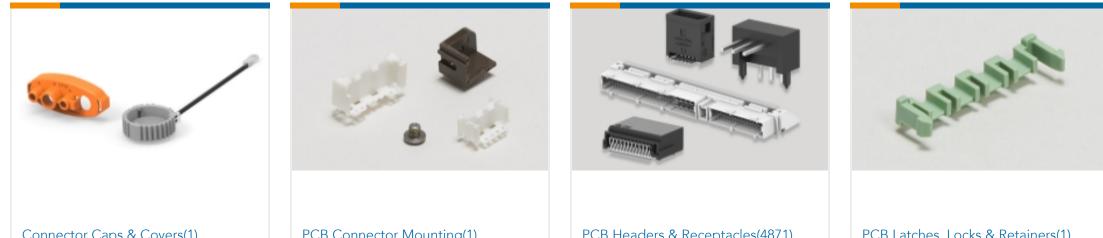
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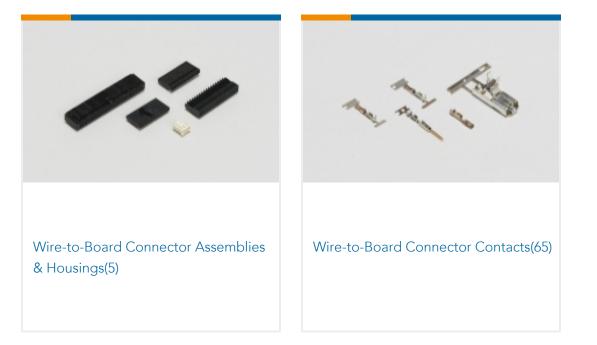




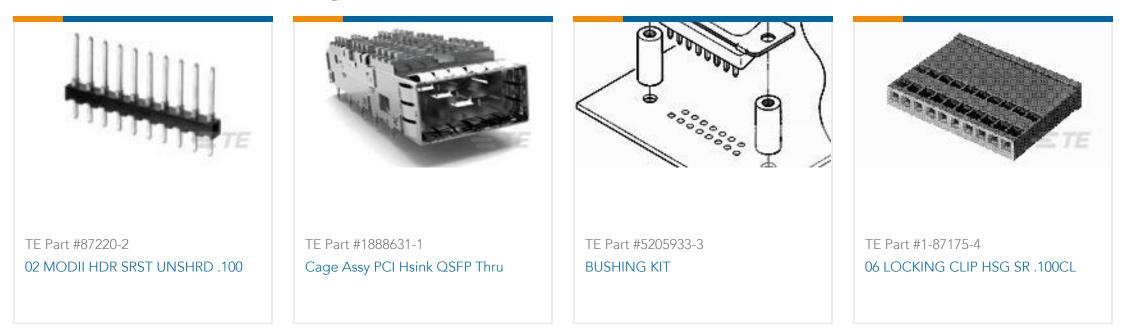
## Also in the Series AMPMODU Headers



Connector Caps & Covers(1)	PCB Connector Mounting(1)	PCB Headers & Receptacles(48/1)	PCB Latches, Locks & Retainers(1)



## **Customers Also Bought**



PCB Mount Header, Vertical, Board-to-Board, 18 Position, 2.54 mm [.1 in] Centerline, Fully Shrouded, Gold, Through Hole - Solder, AMPMODU Headers





### Documents

### Product Drawings 18 MODII HDR DRST SHRD .100CL

English

### **CAD** Files

3D PDF

3D

**Customer View Model** 

ENG\_CVM\_CVM\_5-103168-7\_M.2d\_dxf.zip

English

Customer View Model

ENG\_CVM\_CVM\_5-103168-7\_M.3d\_igs.zip

English

Customer View Model

### ENG\_CVM\_CVM\_5-103168-7\_M.3d\_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Datasheets & Catalog Pages AMPMODU\_INTERCONNECTION\_SYSTEM\_SECTION5

English